Engineering Development Model

RF Transformer

TCM4-EE8271

Impedance Ratio: 4

Important Note

This model has been designed, built and tested in our engineering department. Performance data represents model capability. At present it is a non-catalog model. On request, we can supply a final specification sheet, part number and price/delivery information.



Please click "Back", and then click "Contact Us" for Applications support.

CASE STYLE: DB714

ELECTRICAL SPECIFICATIONS 50Ω @ +25°C					
Parameter		Min.	Тур.	Max.	Units
Frequency		0.5		100	MHz
Insertion Loss *	3 dB Bandwidth		0.5 - 100		MHz
	2 dB Bandwidth		0.5 - 100		MHz
	1 dB Bandwidth		0.5 - 100		MHz
Ampitude Unbalance	over 3dB Bandwidth		0.5		dB
	over 1dB Bandwidth		0.1		dB
Phase Unbalance	over 3dB Bandwidth		5.0		deg.
	over 1dB Bandwidth		1.00		deg.

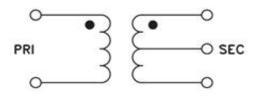
Note:

^{*} Insertion Loss is referenced to mid-band loss, 0.37dB typ.

MAXIMUM RATINGS				
Operating Temperature -20°C to 85°C				
Storage Temperature	-55°C to 100°C			
RF Power	0.25 W			
DC Current	30 mA			

PIN CONNECTIONS		
PRIMARY DOT	6	
PRIMARY	4	
SECONDARY DOT	1	
SECONDARY	3	
SECONDARY CT	2	

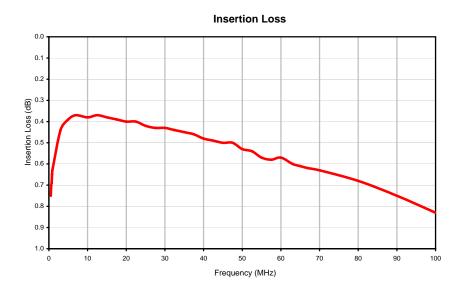
Configuration: A

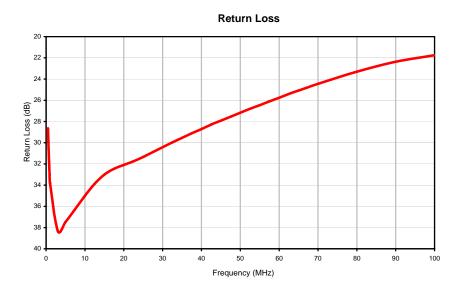


Typical Performance Data

FREQUENCY (MHz)	INSERTION LOSS (dB)	RETURN LOSS (dB)
0.50	0.75	28.64
0.60	0.70	29.95
0.70	0.69	31.09
0.80	0.65	32.09
0.90	0.63	33.00
1.00	0.62	33.79
3.00	0.44	38.33
5.00	0.39	37.47
7.00	0.37	36.50
10.00	0.38	35.00
12.50	0.37	33.88
15.00	0.38	33.01
17.50	0.39	32.46
20.00	0.40	32.10
22.50	0.40	31.75
25.00	0.42	31.34
27.50	0.43	30.88
30.00	0.43	30.42
32.50	0.44	29.97
35.00	0.45	29.54
37.50	0.46	29.11
40.00	0.48	28.72
42.50	0.49	28.29
45.00	0.50	27.92
47.50	0.50	27.55
50.00	0.53	27.17
52.50	0.54	26.80
55.00	0.57	26.46
57.50	0.58	26.10
60.00	0.57	25.76
63.00	0.60	25.33
65.00	0.61	25.08
67.00	0.62	24.83
70.00	0.63	24.45
80.00	0.68	23.30
90.00	0.75	22.37
100.00	0.83	21.75

Typical Performance Curves





Case Style

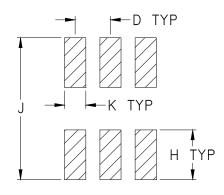


DB714

Outline Dimensions

SEE NOTE 3 D TYP→ SEE NOTE 3 COMPONENT AREA +.005 Ε -.009.000 .008 5 G TYP C MAX ^LPLASTIC SHAPE ADJACENT TO LEADS PICK & PLACE MAY VARY SURFACE AREA (.03X.075)MIN.

PCB Land Pattern



Suggested Layout, Tolerance to be within ±.002

CASE #	A	В	С	D	Е	F	G	Н	J	K	WT. GRAM
DB714	.160	.150	.160	.050	.040	.025	.028	.065	.190	.030	15
DB/14	(4.06)	(3.81)	(4.06)	(1.27)	(1.02)	(0.64)	(0.71)	(1.65)	(4.83)	(0.76)	.13

Dimensions are in inches (mm). Tolerances: 2 Pl. \pm .01; 3Pl. \pm .005

Notes:

- 1. Case material: Plastic.
- 2. Termination finish:

For RoHS Case Styles: Tin plate over Nickel plate. All models, (+) suffix. For RoHS-5 Case Styles: Tin-Lead plate. All models, no (+) suffix.

3. Lead #1 identifier shall be located in the cross-hatched area shown. Identifier may be either a molded or marked feature.



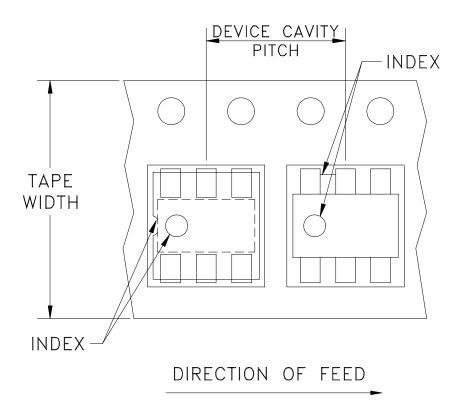


P.O. Box 350166, Brooklyn, New York 11235-0003 (718) 934-4500 Fax (718) 332-4661 For detailed performance specs & shopping online see Mini-Circuits web site

The Design Engineers Search Engine Provides ACTUAL Data Instantly From MINI-CIRCUITS At: www.minicircuits.com

Tape & Reel Packaging TR-F47

DEVICE ORIENTATION IN T&R



Tape Width,	Device Cavity	Reel Size,	Devices per Reel
mm	Pitch, mm	inches	see note
12	8	13	1000, 2000
		7	20, 50, 100, 200, 500

Note: Please consult individual model data sheet to determine device per reel availability.

Mini-Circuits carrier tape materials provide protection from ESD (Electro-Static Discharge) during handling and transportation. Tapes are static dissipative and comply with industry standards EIA-481/EIA-541.

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Environmental Specifications

ENV02

All Mini-Circuits products are manufactured under exacting quality assurance and control standards, and are capable of meeting published specifications after being subjected to any or all of the following physical and environmental test.

Specification	Test/Inspection Condition	Reference/Spec
Operating Temperature	-20° to 85°C Ambient Environment	Individual Model Data Sheet
Storage Temperature	-55° to 100° C Ambient Environment	Individual Model Data Sheet
Humidity	90 to 95% RH, 240 hours, 50°C	MIL-STD-202, Method 103, Condition A, Except 50°C and end-point electrical test done within 12 hours
Thermal Shock	-55° to 100°C, 100 cycles	MIL-STD-202, Method 107, Condition A-3, except +100°C
Solder Reflow Heat	Sn-Pb Eutetic Process: 225°C peak Pb-Free Process 245° - 250°C peak	J-STD-020, Table 4-1, 4-2 and 5-2, Figure 5-1
Solderability	10X Magnification	J-STD-002, 95% Coverage
Vibration (High Frequency)	20g peak, 10-2000 Hz, 12 times in each of three perpendicular directions (total 36)	MIL-STD-202, Method 204, Condition D
Mechanical Shock	50g, 11 ms, 1/2-sine, 18 shocks: 3 each direction, each of 3 axes	MIL-STD-202, Method 213, Condition A
Marking Resistance to Solvents	Isopropyl alcohol + mineral spirits at 25°C; terpene defluxer at 25°C; distilled water + proylene glycol monomethyl ether + monoethanolamine at 63°C to 70°C	MIL-STD-202, Method 215

ENV02 Rev: A

02/25/11

M130240 File: ENV02.pdf

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